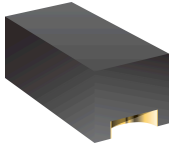


# MATERIAL DECLARATION SHEET



Material Number	CD0603 Series			
Product Line	Diode Products			
Compliance Date	1 Jan 2005			
RoHS Compliant	<b>Yes</b>	MSL	<b>1</b>	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	FR-5 BOARD	Substrate/ Terminal	1.357	Copper	7440-50-8	29.34%	<b>12.16</b>	41.45
				Nickel	7440-02-0	4.762%	1.97	
				Gold	7440-57-5	0.155%	0.064	
				Lead	7439-92-1	0.002%	0.0008	
				Epoxy resin	68928-70-1	65.74%	27.249	
2	Wafer	Diode	0.029	Silicon	7440-21-3	94.21%	0.838	0.89
				Aluminum	7429-90-5	0.44%	0.0039	
				Titanium	7440-32-6	0.08%	0.0007	
				Gold	7440-57-5	5.20%	0.046	
				Arsenic	7440-38-2	0.07%	0.0006	
3	Al Wire	Conductor	0.001	Aluminum	7429-90-5	99%	0.0297	0.03
				Silicon	7440-21-3	1%	0.0003	
4	Silver paste	Welding	0.006	Silver	7440-22-4	78.5%	0.1413	0.18
				Epoxy	9003-36-5	21.5%	0.0387	
5	Molding Compound	Outer	1.881	Silica fused	60676-86-0	85%	48.8325	57.45
				Epoxy resin	68928-70-1	8%	4.596	
				Phenol resin	29690-82-2	4%	2.298	
				Antimony Trioxide	1309-64-4	1.4%	0.8043	
				Brominated Epoxy resin	68541-56-0	1.4%	0.8043	
			Carbon Black	1333-86-4	0.2%	0.1149		
		Total weight	<b>3.274</b>					

This Document was updated on:

# MATERIAL DECLARATION SHEET

---

**BOURNS®**

**Important remarks:**

1. It is the responsibility of the user to verify they are accessing the latest version.